



# TEAM PACIFIC CORPORATION PROCESS TRAVELLER



\*MO853128\*

CUSTOMER	SemiQ Inc.	P.T. #	MO853128 (MO853123 - MO853152)	START DATE	17-FEB-2024
PKG TYPE	ENG'G SEMIQ SOT227 6W(5-12,1-6) AL 2D	S.O. #	96001559	ASSY. DATE	19-FEB-2024
DEVICE	227.GCMS080B120S1-E1 081PDBSSKIUISFTLLMG	BD NO. / REV.	BD-0081-SEMIQ rev.03	SHIP-OUT DATE	15-MAR-2024
LOT #	U45373.U4376C	P.O. #	220316	START QTY.	400

## SPECIAL INSTRUCTIONS.

ENG'G EVALN ATTN: RACHELL A. / NPQ  
REFER TO CEBR ATTACHED FOR SPECIAL INSTRUCTIONS

Tray Number(s): A-007

GCMS080B120S1-E1-PT  
GCMS080B120S1-E1-OT

## SHIP TO:

SemiQ Inc.  
20692 Prism Place Lake Forest

CA, USA 92630

## OPERATIONS:

OPERATIONS	SPEC NO.	CONDITIONS	MACH NO.	OPTR NO.	DATE START/TIME	DATE STOP/TIME	QTY IN	QTY OUT	YLD	QA
Wafer Saw for 13 Feb 24	TPAS-2001		0AD33TD	10381	17 Feb 24 / 3:25 PM	17 Feb 24 / 5:28 PM	400	400	100%	
Die Plate - Automated for 23 Feb 24	REFER TO CEBR		DS-01	N/A	19 Feb 24 / 6:00 PM	19 Feb 24 / 6:30 PM	400	400	100%	
2nd Opt. Inspection for 23 Feb 24	TPAS-2005		LPC	10272	19 Feb 24 / 7:15 PM	19 Feb 24 / 7:33 PM	400	400	100%	
Die Attach for 19 Feb 24	TPAS-2134		BTU#03	7406, 9169	19 Feb 24 / 9:05 PM	19 Feb 24 / 9:09 PM	400	400	100%	
Wirebond for 23 Feb 24	TPAS-2191		CH-21	4236, 7022	23 Feb 24 / 11:45 AM	23 Feb 24 / 8:28 PM	400	400	100%	
3rd Opt. Insp. for 23 Feb 24 (u)	TPAS-2137		CH-02	9787, 9705	23 Feb 24 / 12:20 PM	23 Feb 24 / 3:40 PM	400	400	100%	
Mold for 24 Feb 24	TPAS-2140		PCS-B	9787, 9705	23 Feb 24 / 12:20 PM	23 Feb 24 / 3:40 PM	400	400	100%	
Chemical Deflash	TPAS-2122		LPS	9787	23 Feb 24 / 12:20 PM	23 Feb 24 / 3:40 PM	400	396	99%	
Post Mold Cure	TPAS-2142		MP-15	10385	24 Feb 24 / 8:05 AM	24 Feb 24 / 11:30 AM	396	396	100%	
Laser Mark	TPAS-2141		1MM-01	4011 10545	24 Feb 24 / 2:00 PM	24 Feb 24 / 5:45 PM	396	396	100%	
Trim	TPAS-2394		34	10541	24 Feb 24 / 4:15 PM	24 Feb 24 / 8:15 PM	396	396	100%	
First Form	TPAS-2394		LASEROI	G831	24 Feb 24 / 12:46 AM	24 Feb 24 / 1:16 AM	396	396	100%	
Final Form	TPAS-2394		HPT	9850	26 Feb 24 / 9:45 AM	26 Feb 24 / 11:24 AM	396	396	100%	
6th Opt. Inspection	TPAS-2394		HP05	6819	26 Feb 24 / 9:49 AM	26 Feb 24 / 11:29 AM	396	396	100%	
Isolation Test	TPAS-2394		AP2	10935	26 Feb 24 / 9:52 AM	26 Feb 24 / 11:30 AM	396	396	100%	
UIS Test	TPAS-2354		N/A	10836 10779, 10834	26 Feb 24 / 11:15 AM	26 Feb 24 / 2:00 PM	396	389	98.23%	
Final Test	TPAS-2354		#2	10813	26 Feb 24 / 9:53 AM	26 Feb 24 / 11:31 AM	396	389	100%	
QA Final Test Buy-off	TQAI-3143		UIS#08	10717	26 Feb 24 / 2:30 PM	26 Feb 24 / 4:24 PM	389	385	98.97%	
Pack	TPAS-2123		SA-C	10535	26 Feb 24 / 4:30 PM	26 Feb 24 / 5:05 PM	385	379	98.44%	
			SA-C	10078	26 Feb 24 / 5:05 PM	26 Feb 24 / 5:05 PM	80	80	100%	
			N/A	G245	26 Feb 24 / 11:11 PM	26 Feb 24 / 11:21 PM	379	379	100%	

TPC  
QA # 353  
23 Feb 24TPC  
QA # 338  
26 Feb 24TPC  
QA # 337  
26 Feb 24





\*MO853128\*

...Continuation of First Page

## MATERIALS

STOCK NO.	DESCRIPTION	LOT NUMBER	QUANTITY
GPE.GP2T080A120X	DIE GP2T080A120X	U46373,U43768	400
GPE.GP3D010A120X	DIE SiC SBD (10A/1200V) GP3D010A120X (Size: 95 x 95 mils)		400
TPC.QIO02001	Hub-type Blade part number:ZH14-SD2000-V1-90DD; Supplier: Aliba	H230905CM910 P5	0.01
TPC.QIO09230	Dicing tape, DENKA-UHP-110M3 UV Curable : Size 230mmx100m	2105-5014A	0.11
TPC.QIC02102	MTI Hyper-Pro Dicing Solution Surfactant : Alibata ; TMPS-4033 Re	MBW314H 30 P2 30 3014 29	0.02
TPC.RK05003A	BASE PLATES SOT-227 STAMPED (SDI) MATERIAL: C1220, FULL	B2400000 1-11	405
TPC.RK01043	LEADFRAMES, SOT-227 PAD B STAMPED, PLATING SPECS: FU	B23000278-325	405
TPC.RK04067	Substrate, Pad B AlN, Conductive Metal: Cu, Drawing# SU-0311-D	20231117- R	405
TPC.RN02032J	PREFORM, SOLDER, 92.5PB/5SN/2.5AG, SIZE: 0.255*(+/-0.010")	F43947A1	1,615.2
TPC.RN02041	Disc Solder Pb Sn (5) Ag (2.5) size: 1.4 x 0.51 mm disc ; SPECS	21226	403.8
TPC.RN02049	SOLDER PREFORM, 92.5Pb/5Sn/2.5Ag; SIZE: 4X68.5X68.5 MILS	F45889C2	403.8
TPC.RN01021	BW AL-Bond 12mil 100M 07A TS-500 GMS Min EL 10-30% 99.99%	9016621907	17.12
TPC.RN01049	WIRE, ALUM, 6 MILS, 99.99%, TENSILE: 80 GMS, ELONG: 5-12%	MS019473-A	2.04
TPC.RN05013	Molding Compound Hysol MG15F-0140 mini pellet (18mm x 9.5 gr	023GA1369	3,835.90
TPC.RN06002	NUTS SOT-227 M4-0.77MM P/N 934 HEX NUT NICKEL PLATED	120723	1,600
TPC.RN06001	BOLTS SOT-227 M4X8.5MM PAIL PAN HD SEMS W/ LOCK AND	001620	1,600



332 16 24 FEB. 24  
TOP/SIDE MARK INSTRUCTION

4  
1  
Semi

REFER TO CEBR

5  
2

GCMSP080812051-E1  
2408 MO815128

BACK/BOTTOM MARK INSTRUCTION

[illegible]

TSOP-9001-F1



## PROCESS TRAVELLER CHECKLIST FORM

MO #: 853128

OPERATION	OPTR #	DATE SHIFT	ACTIVITY TO ACCOMPLISH
DIE PLATE	N/A	19 Feb 24 / R	Plate Card Traceability Lot No. : 096373 4 043767 No. of Grid Plate : 4, 4 Device No. : GCM5080812051 Cabinet No. : NA Quantity : 900 Tray No. : A-003
SETUP	10705	19 Feb 24 / b	Railcode #: 025 Machine type (BTU, ESEC, Centro) : #03 if Centro, Prog # H/A With special / Eng'g instruction? YES <input checked="" type="checkbox"/> NO <input type="checkbox"/> No. of Grid Plates : 4-4 Tray No. 2-007 Indicate Magazine/ tray #. Quantity # of Defects and Operator # 021-50 ✓ 040-50 ✓ 142-50 ✓ 024-50 ✓ 049-50 ✓ N-011-50 - Cw/mis D) (w/IV-5585 011-50 ✓ 148-50 ✓
LEADBOND	4238 7022	23 Feb 24 / O 23 Feb 24 / S	BD# on PT : B0008 Semi Q 03 BD# Actual (card): B0008 Semi Q 03 BD# Program (display): B00081-Semi Q-12 / B00081-D3-6C Check Set-up Checklist on TCM (if done?) : Yes Check magazine # @ D/A versus Actual : 4238 With special / Eng'g instruction? YES <input checked="" type="checkbox"/> NO <input type="checkbox"/> Indicate Magazine/ tray #. Quantity # of Defects and Operator # 095-50 ✓ 14-101-50 ✓ 15-090-50 ✓ 14-011-50 ✓ 4238 ✓ 14-115-50 ✓ 142-50 ✓ 14-012-50 ✓ 14-118-50 ✓
3 <sup>RD</sup> OPTICAL	9767	23 Feb 24 / G	Check magazine # @ W/B versus Actual : Yes Indicate Magazine/ tray #. Quantity # of Defects and Operator # 080-50 ✓ 0018-50 ✓ 184m-50 ✓ 096m-50 ✓ 195-50 ✓ 113m-50 ✓ 006-50 ✓ 197-46 ✓ Loop height checking: Passed / Failed:
MOLD	10385	24 Feb 24 / D	Write "COMPLETED" if previous operation is Done: Completed Mold compound type: Kysol (m) Temp requirement: 175-185°C With special / Eng'g instruction? YES <input type="checkbox"/> NO <input checked="" type="checkbox"/> Tool Serials # / Tool # 1304-04 mcp Indicate Magazine/ tray #. Quantity # of Defects and Operator # 22-029 - 100 22-040 - 100 15-026 - 100 R011 - 96
DEFLASH	4011 1004	24 Feb 24 / S	Indicate Magazine/ tray #. Quantity # of Defects and Operator # 22-029 - 100 22-040 - 100 15-026 - 100 R011 - 96
MARK	6831	24 FEB 24 / G	D/A Date (Origin): N/A Temp/ Oven #: N/A Date Code: 2408 Check PT for making instruction OK Indicate Magazine/ tray #. Quantity # of Defects and Operator # 22-029-100 R011-96 22-040-100 15-026-100
PMC	10541	24 FEB 24 / S	PMC Time Required: 2 HRS Temp/ Oven #: 190 ± 5°C / 30 Indicate Magazine/ tray #. Quantity # of Defects and Operator # 22-029 - 100 15-026 - 100 22-040 - 100 R011 - 96
TRIM	9850	26 Feb 24 / D	Lead cut requirement: STD Lead Finish : S/D <input type="checkbox"/> S/P <input type="checkbox"/> TP <input type="checkbox"/> 22-040-100 R011-96 15-026-100 22-029-100
FINAL VISUAL INSPECTION	N/A	N/A	Utilized KI Substrate at Die Attach? YES <input type="checkbox"/> NO <input type="checkbox"/> For Vishay Builds only: *IF YES, Perform void / delamination check for all KI substrate (For the list of KI substrate stock number, refer to TAFC 1324 para 6.1) *IF NO, DO NOT PERFORM VOID / DELAMINATION CHECK CVI-6819 CV2-10813
FINAL TEST	10025	26 Feb 24 / S	Job # on PT : N/A Test program requirement: GCM5080812051-E1-F1 Part # on ARA / Rev : GCM5080812051-E1-F1



- (Die) CP27030M20x  
 - Wafer # 12 - observed die bond peel-off  
 during auto die plate.  
 - for 100% die bond inspection.

19 FEB 24

Processed at alphasem Auto Die  
 Sorter machine.

*G. H. H.*  
 19 FEB 24

CSAM SAMPLING DONE  
 @ ebox

22 Feb. 24 JH 0/40

DL: 10411

Howe to Howe Passed 5/5

CSAM Sampling done - PMC  
 24 Feb. 24 JH

CSAM sampling done  
 @ ebox

26 Feb. 24 JH

FVS

10097-175

10838-113

10834-100

1 ACCEPT

MS - 7

396

CRACK SAMPLING DONE  
 26 FEB 24

Tesec Mon Feb 26 17:32:31 2024

Station C Test by Branch / Polarity NPN  
FileName GCMS080B120S1-E1\_FT  
Comment MO853128 LOT#U46373 OPTR#10025

SumBin  
SumBin Total 0 0.0 %

Bin SortName Sub Percent

24 CONTACT FAIL	0	0.0 %
4 OS FAIL	5	1.3 %
4 VTH FAIL	1	0.3 %
14 BV FAIL	0	0.0 %
8 RDSON FAIL	0	0.0 %
11 VF FAIL	0	0.0 %
10 DELTA VF	0	0.0 %
9 ID FAIL	0	0.0 %
1 GCMS080B120S1-E ✓	379	98.4 %
5 GATE FAIL	0	0.0 %
4 REJECT	0	0.0 %

Total 385

TPC  
CA # 338  
# 26 FEB 24

1x140  
1x2 142

1x20  
1x1 29

1x100  
1x10 110

1x1 = 1

1x10  
1x1 97

379  
9  
388

NO - NO. 1000 NO. 1000  
3 CONTINUING NO. 1000



Tesec Mon Feb 26 17:41:41 2024

Station C Test by Branch Polarity NPN  
FileName GCMS080B120S1-E1\_QA /  
Comment MO853128 LOT#U46373 OPTR#10025 B/O

SumBin

SumBin Total 0 -0.0 %

Bin SortName

Sub Percent

24 CONTACT FAIL	0	0.0 %
4 OS FAIL	0	0.0 %
4 VTH FAIL	0	0.0 %
14 BV FAIL	0	0.0 %
8 RDSON FAIL	0	0.0 %
11 VF FAIL	0	0.0 %
9 ID FAIL	0	0.0 %
5 GATE FAIL	0	0.0 %
1 GCMS080B120S1-E	80	100.0 %
4 REJECT	0	0.0 %

Total

80

TSC  
CA # 338  
ASC  
26 FEB 24

Tesec Mon Feb.26 17:05:36 2024

Station C Test by Branch Polarity NPN  
FileName GCMS080B120S1-E1 FT ✓  
Comment M0853128 LOT#U46373 OPTR#10717 SAMPLING UIS#08

-----  
SumBin  
SumBin Total 0 0.0 %  
-----

-----  
Bin SortName Sub Percent  
-----  
24 CONTACT FAIL 0 0.0 %  
4 OS FAIL 0 0.0 %  
4 VTH FAIL 0 0.0 %  
14 BV FAIL 0 0.0 %  
8 RDSON FAIL 0 0.0 %  
11 VF FAIL 0 0.0 %  
10 DELTA VF 0 0.0 %  
9 ID FAIL 0 0.0 %  
1 GCMS080B120S1-E ✓ 10 100.0 %  
5 GATE FAIL 0 0.0 %  
4 REJECT 0 0.0 %  
-----

Total 10

TPC  
DA # 338  
5.01717.24





TEAM PACIFIC CORPORATION  
CUSTOMER ENGINEERING BUILD REQUEST

CEBR#:

SQ24-SOT227-11

(PLASTICS)

15-Feb-24

Product Stage > Purpose:	Pre-production →	New package	Production Start Time:	over 12 months	Business Type:	IDM
Customer	SemiQ Inc.		Ship To	SemiQ Inc.		
Contact Person	Peggy Thron			20692 Prism Place		
Telephone				Lake Forest California 92630		
E-mail Address	<pthron@semiq.com>			USA		
Facsimile			Bill To	SemiQ Inc.		
Forwarder/Account #						
Package Type	SOT-227 Pad B		Build Qty	12,073		
Device Type	GCMS080B120S1-E1		Run:	8		
Lot No.	MOSFET: U46373 / Diode: U43768		Product Application / Grade	Commercial		

<b>1</b> <b>WAFER SAW</b>	Die Type 1:	SiC MOS; GPE.GP2T080A120X	Qty	<b>1</b>	<b>10</b> <b>TRIM</b>	<input checked="" type="checkbox"/> Trim/Crop 1	<input type="checkbox"/> Trim/Crop 2
	Die Size:	111 x 111 mils					
	Die Thickness	6~8 mils			<b>11</b> <b>FORM</b>	<input checked="" type="checkbox"/> Form 1	<input checked="" type="checkbox"/> Form 2 <input checked="" type="checkbox"/> Form 3
	Wafer Size:	6 inches				Mat'l Type 1:	Bolts: TPC.RN06001 / TPC.RN06010
	Die Type 2:	SiC DIODE; GPE.GP3D010A120X	Qty	<b>1</b>		Mat'l Type 2:	Nuts: TPC.RN06002 / TPC.RN06011
	Die Size:	95 x 95 mils			<b>12</b> <b>ISOLATION</b>	<input checked="" type="checkbox"/> 100%	<input type="checkbox"/> Sampling
	Die Thickness	6~8 mils			<b>13</b> <b>4TH OPT INSP.</b>	<input checked="" type="checkbox"/> 100%	<input type="checkbox"/> Sampling
	Wafer Size:	6 inches			<b>14</b> <b>FINAL TEST</b>	<input checked="" type="checkbox"/> Yes	Requirement: w/ UIS
<b>2</b> <b>DIE PLATE</b>	<input type="checkbox"/> Manual	<input checked="" type="checkbox"/> Automatic	<input type="checkbox"/> Viking			Datasheet / Test Program Available: See customer format	
<b>3</b> <b>2ND OPT INSP.</b>	<input type="checkbox"/> Military	<input checked="" type="checkbox"/> Commercial			<b>15</b> <b>PACK</b>	<input checked="" type="checkbox"/> TPC Std	<input type="checkbox"/> Customer Std.
<b>4</b> <b>DIE ATTACH</b>	<input checked="" type="checkbox"/> Manual	<input type="checkbox"/> Automatic	<input type="checkbox"/> Semi-Auto			Mat'l Type 1:	SOT227 clear tube: TPC.IS02059
	<input type="checkbox"/> Eutectic	<input type="checkbox"/> Epoxy	<input checked="" type="checkbox"/> Soft Solder			Mat'l Type 2:	End Plug: TPC.IS08026
	Mat'l Type 1:	BP: TPC.RK05003A / TPC.RK05012		Qty		Mat'l Type 3:	Inner Box: TPC.IS01010
	Mat'l Type 2:	PB LF: TPC.RK01043 / TPC.RK01089		Qty		Mat'l Type 4:	Master Box: TPC.IS01029
	Mat'l Type 3:	Sub: TPC.RK04010 / TPC.RK04067		Qty		Mat'l Type 5:	Bubble Sheet: TPC.IS07003
	Solder Type 1:	BP-Sub-LF Pref: TPC.RN02032J		Qty		Mat'l Type 6:	Shipping label: TPC.IS10052
	Solder Type 2:	MOSF-LF Disc: TPC.RN02041		Qty		Mat'l Type 7:	Plastic bag: TPC.IS06001
	Solder Type 3:	Diode-LF Pref: TPC.RN02049		Qty			
	Aligner Ref. Drawing No.	AD-0094-IP rev. 2		Qty			
				128			
<b>5</b> <b>WIREBOND/ GATELIFT/ 3RD OPT. INSP.</b>	<input type="checkbox"/> Manual	<input checked="" type="checkbox"/> Automatic			<b>OTHER REQUIREMENTS:</b>		
	Wire Type:	Aluminum			<b>OTHERS</b>	Requirement:	
	Wire Size 1:	12 mils wire; TPC.RN01021	Qty	<b>5</b>	<b>SPECIAL REQUIREMENTS:</b>		
	Wire Size 2:	6 mils wire; TPC.RN01049	Qty	<b>1</b>	Critical Processes:	ALL PROCESSES	
	<input checked="" type="checkbox"/> 100%	<input type="checkbox"/> Sampling			Build Attention to:	QUAL ENGRS	
	<input checked="" type="checkbox"/> LPS	<input type="checkbox"/> HPS			1. Used inked dice for set-up purposes		
<b>6</b> <b>MOLD</b>	Mat'l Type:	Hysol MG15F; TPC.RN05002 / TPC.RN05013			2. To be processed at Die Plate via Alphasm machine. If in case that the machine is not available, the process can be done manually.		
<b>7</b> <b>CHEM. DFLASH</b>	Mat'l Type:	M-Pyrol; TPC.IC02014			3. No rework at FOL unless approved by the customer		
<b>8</b> <b>POST MOLD CURE</b>	Time:	2 Hours			4. Qualified both at BTU and VLO		
	Temp:	190 +/- 5°C			5. Qualified both at MGP and CVL		
<b>9</b> <b>LASERMARK</b>	<input type="checkbox"/> Top <input checked="" type="checkbox"/> Side <input type="checkbox"/> Bottom				6. Refer to the Build sheet for the marking lay-out		
	Lay-Out:	BD-0081-SEMIQ rev. 03			7. TEs can directly communicate test result to customer		
					8. For any concern, please call attention of Qual/BD.		

REF. DOCUMENTS:	<input type="checkbox"/> Cust. Specs	<input checked="" type="checkbox"/> Process Flow	TAFC 1066	<input checked="" type="checkbox"/> PO/Invoice	220316
	<input checked="" type="checkbox"/> Bonding Diagram	<input checked="" type="checkbox"/> Control Plan	TPCP 4003	<input type="checkbox"/> Ref. Standard	
	<input checked="" type="checkbox"/> Marking Documents	<input type="checkbox"/> Die/Wafer Drawing		<input type="checkbox"/> Others	

Initiator: 15 Feb 24  
Richard A. ORIGINATOR

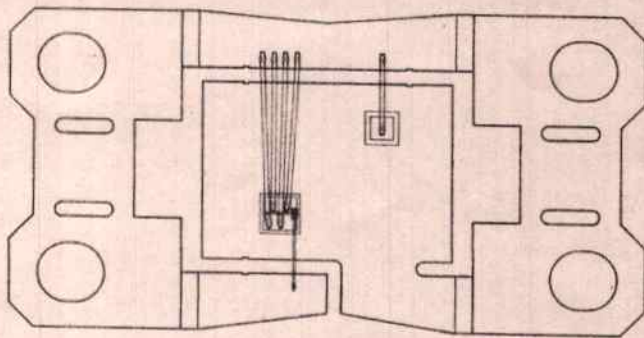
15 Feb 24  
Richard P. QE / NPQE

15 Feb 24  
Marking Sales NPQ - AVP

15 Feb 24  
VBM EVP / COO

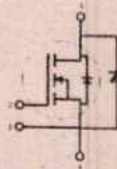


## BUILD DIAGRAM

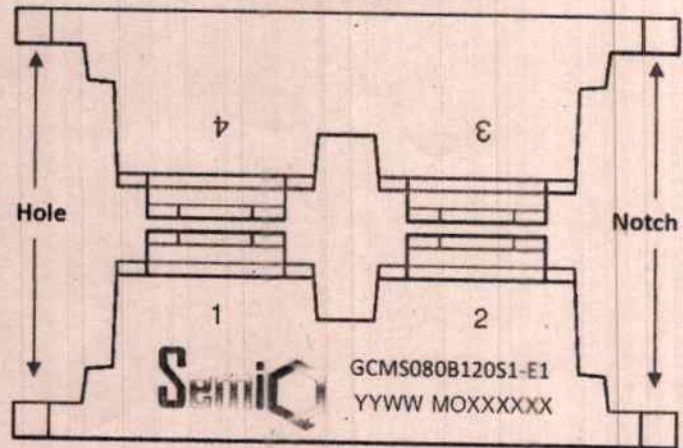


Die Aligner: AD-0094-IP Rev.01

Circuit Diagram



## LASER MARKING DIAGRAM



Terminal Mark = 1, 2, 3, and 4  
Logo: Company Name  
Device Name = GCMS080B120S1-E1  
YYWW = Date Code  
YY - Last 2 digits of the Year WW - 2 digits Mold Week  
MOXXXXXX = Process Traveller #

## ISOLATION TEST

Voltage @60Hz = 4.0kV; Max. Leakage Current = 1.0mA Time = 10 secs.

Note: Use 60secs. for the first 2units.

## ELECTRICAL TEST REQUIREMENTS

Item	Symbol	Description	Test Condition @ 25°C	Min	Max	Unit
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See separate file for complete details of Final Test and AQL Test specification (Customer's format)

## BILL OF MATERIALS

Operation	Description	Ref. Stock Number	Quantity
Die Attach	Die SiC SBD (10A/1200V) GP3D010A120X (Size: 95 x 95 mils)	GPE.GP3D010A120X	1
	Die SiC MOSFET (20A/1200V) (111.42 mils x 111.42 mils)	GPE.GP2T080A120X	1
	Base Plate: Full Nickel	TPC.RK05003A / TPC.RK05012	1
	Lead Frame: Pad B	TPC.RK01043 / TPC.RK01089	1
	Substrate: Metallized AlN (Size: 700x 500mils)	TPC.RK04010 / TPC.RK04067	1
	Solder Preform: 92.5Pb/5Sn/2.5Ag (Size: 255x350mils) - BP to Subs to LF	TPC.RN02032J	4
	Solder Disc: 92.5Pb/5Sn/2.5Ag (Size: 55 mils) - MOSFET to LF	TPC.RN02041	1
Wire Bond	Solder Preform: 92.5Pb/5Sn/2.5Ag (Size: 68.5 x 68.5) - SBD to LF	TPC.RN02049	1
	12mils Aluminum wire (99.99%) - Std Bond for MOSFET Source and SBD Anode	TPC.RN01021	5
Mold	6mils Aluminum wire (99.99%) - Std Bond for MOSFET Gate	TPC.RN01049	1
	EMC Hysol MG15F-0140 (Conventional or MGP)	TPC.RN05002 / TPC.RN05013	-
Form	Bolts (M4x8.5mm)	TPC.RN06001 / TPC.RN06010	4
	Nuts (M4-0.77mm)	TPC.RN06002 / TPC.RN06011	4
Pack	Anti-static tube	TPC.IS02003 / TPC.IS02059	-
	End Plug	TPC.IS08026	2/tube
	Pink Plastic	TPC.IS06001	-
	Bubble Sheet	TPC.IS07003	-
	Intermediate Box	TPC.IS01010	-
	Sticker Label (for Intermediate Box)	TPC.IS10052	1/box

	Name	Function	Signature	Date
Prepared By	Rachell Y. Adriano	CSE		July 18, 2023
Reviewed By	Guian D. Gomez	Mktg. and CS Manager		
Customer Approval	Seok Joo Jang	Sr. Manager	Seok Joo Jang	August 17, 2023



Doc No. : BD-0081-SEMIQ  
Rev. : 03

TSOP-2012-F13